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Semiconductor devices –

Part 16-4: Microwave integrated circuits – Switches

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International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 60747-16-4 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47E/256/FDIS	47E/261/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

SEMICONDUCTOR DEVICES –

Part 16-4: Microwave integrated circuits – Switches

1 Scope

This part of IEC 60747 provides new measuring methods, terminology and letter symbols, as well as essential ratings and characteristics for integrated circuit microwave switches.

There are many combinations for RF ports in switches, such as SPST (single pole single throw), SPDT (single pole double throw), SP3T (single pole triple throw), DPDT (double pole double throw), etc. Switches in this standard are based on SPDT. However, this standard is applicable to the other types of switches.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60617-12, *Graphical symbols for diagrams – Part 12: Binary logic elements*

IEC 60617-13, *Graphical symbols for diagrams – Part 13: Analogue elements*

IEC 60747-1(1983), *Semiconductor devices – Discrete devices and integrated circuits – Part 1: General*
Amendment 3 (1996)

IEC 60747-4, *Semiconductor devices – Discrete devices – Part 4: Microwave devices*

IEC 60748-2, *Semiconductor devices – Integrated circuits – Part 2: Digital integrated circuits*

IEC 60748-3, *Semiconductor devices – Integrated circuits – Part 3: Analogue integrated circuits*

IEC 60748-4, *Semiconductor devices – Integrated circuits – Part 4: Interface integrated circuits*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

Terms related to electrical characteristics

3.1
insertion loss
L_{ins}
ratio of the output power at the switched on port to the input power in the linear region of the power transfer curve P_o (dBm) = $f(P_i)$

NOTE 1 In this region, ΔP_o (dBm) = ΔP_i (dBm).

NOTE 2 Usually the insertion loss is expressed in decibels.

3.2
isolation
L_{iso}
ratio of the output power at the switched off port to the input power in the linear region of the power transfer curve P_o (dBm) = $f(P_i)$

NOTE 1 In this region, ΔP_o (dBm) = ΔP_i (dBm).

NOTE 2 Usually the isolation is expressed in decibels.

3.3
return loss
L_{ret}
ratio of the incident power P_{inc} at the specified port to the reflected power P_{ref} at the same port in the linear region of the power transfer curve P_{ref} (dBm) = $f(P_{inc})$

NOTE 1 In this region, ΔP_{ref} (dBm) = ΔP_{inc} (dBm).

NOTE 2 Usually the return loss is expressed in decibels.

3.4
input power at 1 dB compression
$P_{i(1\ dB)}$
input power where the insertion loss increases by 1 dB compared with insertion loss in linear region

3.5
output power at 1 dB compression
$P_{o(1dB)}$
output power where the insertion loss increases by 1 dB compared with insertion loss in linear region

3.6
turn on time
t_{on}
interval between the lower reference point on the leading edge of the control voltage and the upper reference point on the leading edge of the envelope of the output voltage in the linear region of the power transfer curve P_o (dBm) = $f(P_i)$

NOTE In this region, ΔP_o (dBm) = ΔP_i (dBm).

3.7
turn off time
t_{off}
interval between the upper reference point on the trailing edge of the control voltage and the lower reference point on the trailing edge of the envelope of the output voltage in the linear region of the power transfer curve P_o (dBm) = $f(P_i)$

NOTE In this region, ΔP_o (dBm) = ΔP_i (dBm).

3.8
rise time
$t_{r(out)}$
interval between the lower reference point on the leading edge of the output voltage and the upper reference point on the leading edge of the envelope of the output voltage in the linear region of the power transfer curve P_o (dBm) = $f(P_i)$

NOTE In this region, ΔP_o (dBm) = ΔP_i (dBm).

3.9
fall time
$t_{f(out)}$
interval between the upper reference point on the trailing edge of the output voltage and the lower reference point on the trailing edge of the envelope of the output voltage in the linear region of the power transfer curve P_o (dBm) = $f(P_i)$

NOTE In this region, ΔP_o (dBm) = ΔP_i (dBm).

3.10
adjacent channel power ratio
$P_{o(mod)}/P_{adj}$
ratio of the total power in the specified carrier signal frequency band to total output power in the specified frequency band away from the specified carrier signal frequency, at the specified output power when the modulation signal is supplied

3.11
n-th order harmonic distortion ratio
P_{nth}/P_1
See 3.14 of IEC 60747-16-1(2001).

4 Essential ratings and characteristics

This clause gives ratings and characteristics required for specifying integrated circuit microwave switches.

4.1 Circuit identification and types

4.1.1 Designation and types

Identification of type (device name), category of circuit and technology applied should be given. Microwave switches comprise one category.

4.1.2 General function description

A general description of the function performed by the integrated circuit microwave switches and the features for the application should be made.

4.1.3 Manufacturing technology

The manufacturing technology, e.g. semiconductor monolithic integrated circuit, thin film integrated circuit, micro-assembly, etc. should be stated. This statement should include details of the semiconductor technologies such as Schottky-barrier diode, PIN diode, MESFET, Si bipolar transistor, etc.

IEC 60747-4 should be referred to for terminology and letter symbols, essential ratings and characteristics and measuring methods of such microwave devices.

4.1.4 Package identification

The following statements should be made:

a) chip or packaged form;
b) IEC and/or national reference number of the outline drawing, of drawing of non-standard package including terminal numbering;
c) principal package material, for example, metal, ceramic, plastic.

4.1.5 Main application

The main application should be stated. If the device has restrictive applications, these should be stated here.

4.2 Application description

Information on application of the integrated circuit and its relation to the associated devices should be given.

4.2.1 Conformance to system and/or interface information

It should be stated whether the integrated circuit conforms to an application system and/or an interface standard or a recommendation.

Detailed information concerning application systems, equipment and circuits such as VSAT systems, DBS receivers, microwave landing systems, etc. should also be given.

4.2.2 Overall block diagram

A block diagram of the applied systems should be given if necessary.

4.2.3 Reference data

The most important properties that permit comparison between derivative types should be given.

4.2.4 Electrical compatibility

It should be stated whether the integrated circuit is electrically compatible with other particular integrated circuits, or families of integrated circuits, or whether special interfaces are required.

Details should be given concerning the type of input and output circuits, e.g. input/output impedances, d.c. block, open-drain, etc. Interchangeability with other devices, if any, should also be given.

4.2.5 Associated devices

If applicable, the following should be stated:

– devices necessary for correct operation (list with type number, name and function);
– peripheral devices with direct interfacing (list with type number, name and function).

4.3 Specification of the function

4.3.1 Detailed block diagram – Functional blocks

A detail block diagram or equivalent circuit information of the integrated circuit microwave switches should be given. The block diagram should be composed of the following:

a) functional blocks;
b) mutual interconnections among the functional blocks;
c) individual functional units within the functional blocks;
d) mutual interconnections among the individual functional blocks;
e) function of each external connection;
f) inter-dependence between the separate functional blocks.

The block diagram should identify the function of each external connection and, where no ambiguity can arise, also show the terminal symbols and/or numbers. If the encapsulation has metallic parts, any connection to them from external terminals should be indicated. The connections with any associated external electrical elements should be stated, where necessary.

As additional information, the complete electrical circuit diagram can be reproduced, but not necessarily with indications of the values of the circuit components. The graphical symbol for the function shall be given. Rules governing such diagrams may be obtained from IEC 60617-12 or IEC 60617-13.

4.3.2 Identification and function of terminals

All terminals should be identified on the block diagram (supply terminals, input or output terminals, input/output terminals).

The terminal functions 1) to 4) should be indicated in a table as follows:

Terminal number	Terminal symbol	1) Terminal designation	2) Function	Function of terminal	
				3) Input/output identification	4) Type of input/ output circuits

1) Terminal designation

A terminal designation to indicate the function of the terminal should be given. Supply terminals, ground terminals, blank terminals (with abbreviation NC), non-usable terminals (with abbreviation NU) should be distinguished.

2) Function

A brief indication of the terminal function should be given:

- each function of multi-role terminals, i.e. terminals having multiple functions;
- each function of integrated circuit selected by mutual pin connections, programming and/or application of function selection data to the function selection pin, such as mode selection pin.

3) Input/output identification

Input, output, input/output and multiplex input/output terminals should be distinguished.

4) Type of input/output circuits

The type of input and output circuit, e.g. input/output impedances, with or without d.c. block, etc., should be distinguished.

5) Type of ground

If the baseplate of the package is used as ground, this should be stated.

Example: